


MATERIAL DECLARATION SHEET



Material Number	PTVS6-058C-SH			
Product Line	Semiconductor products			
Compliance Date	Aug 31 st 2014			
RoHS Compliant	Yes	MSL	Level 1	

No.	Construction Element (subpart)	Homogenous Material	Material Weight (g)	Homogenous Material/ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart Mass % of total unit wt.
1	Encapsulation	Epoxy Resin	0.204000	Bisphenol Copolymer	25036-25-3	60.00	6.11	10.18
				Alumina Trihydrate	21645-51-2	15.00	1.53	
				Fused Silica	60676-86-0	20.00	2.04	
				Hydrated Iron Oxide	20344-49-4	1.50	0.15	
				Titanium Dioxide	13463-67-7	1.50	0.15	
				Melamine Cyanurate	3740-57-6	1.50	0.15	
				Amine Adduct	Trade Secret	0.50	0.05	
2	Electrodes	Copper	1.083616	Copper	7440-50-8	99.10	53.57	54.06
				Silver	7440-22-4	0.40	0.22	
				Other, not to declare	-	0.50	0.27	
3	Terminations	Copper	0.459942	Copper	7440-50-8	99.50	22.83	22.94
				Other, not to declare	-	0.50	0.11	
4	Termination Finish	Silver	0.015281	Silver	7440-22-4	100.00	0.76	0.76
5	Chip	Silicon Die	0.095269	Silicon	7440-21-3	87.23	4.15	4.75
				Aluminium	7429-90-5	4.47	0.21	
				Nickel	7440-02-0	7.92	0.38	
				Gold	7440-57-5	0.38	0.02	
6	Die Attach	Solder	0.073483	Lead	7439-92-1	92.50	3.39	3.67
				Tin	7440-31-5	5.00	0.18	
				Silver	7440-22-4	2.50	0.09	
7	Die Coating	Silicone	0.072962	Polysiloxane	63148-62-9	22.11	0.80	3.64
				Chromium Sesquioxide	1308-38-9	5.67	0.21	
				Fumed Silica	112945-52-5	11.11	0.40	
				Filler	trade secret	61.11	2.22	
		Total Weight	2.004553					